

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
TOMOHIDE KATO	10/28/2011
TAKAAKI NODA	10/28/2011
NORIKAZU MIZUNO	10/28/2011
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<b>City:</b>	TOYKO
<b>State/Country:</b>	JAPAN
<b>Postal Code:</b>	1018980
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	14681055
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<b>ATTORNEY DOCKET NUMBER:</b>	HITACHI12-21010033US03
<b>NAME OF SUBMITTER:</b>	DENNIS F. DEFINO, JR.
<b>SIGNATURE:</b>	/DENNIS F. DEFINO, JR./
<b>DATE SIGNED:</b>	03/23/2016
<b>Total Attachments: 2</b>	
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source=Assignment_HITACHI12_21010033US03#page2.tif	

**ASSIGNMENT**

**Norikazu Mizuno, Tomohide Kato, Takaaki Noda**, residing at Toyama, Japan, citizens of Japan (hereafter the undersigned); are the inventor of Method of Manufacturing Semiconductor Device, Semiconductor Device and Substrate Processing Apparatus for which the undersigned executed an application for United States Letters Patent, U.S. Patent Application No. 14/681,055, filed April 7, 2015, 2011.

The undersigned hereby authorizes assignee or assignee's representative to insert the Application Number and the filing date of this application if they are unknown at the time of execution of this assignment.

**Hitachi Kokusai Electric Inc.**, [ a / an] company, having a principal place of business at

14-1, Sotokanda 4-chome, Chiyoda-ku, Tokyo 1018980, Japan  
(hereafter referred to as the assignee), is desirous of acquiring the entire right, title, and interest in said invention, all applications for, and all letters patent issued on said invention.

For good and valuable consideration, the receipt and sufficiency of which is acknowledged, the undersigned, intending to be legally bound, does hereby sell, assign, and transfer to the assignee and assignee's successors, assigns, and legal representatives the entire right, title, and interest in said invention and all patent applications thereon, including, but not limited to, the application for United States Letters Patent entitled as above, and all divisions and continuations thereof, and in all letters patent, including all reissues and reexaminations thereof, throughout the world, including the right to claim priority under the Paris Convention or other treaty.

It is agreed that the undersigned shall be legally bound, upon request of the assignee, to supply all information and evidence relating to the making and practice of said invention, to testify in any legal proceeding relating thereto, to execute all instruments proper to patent the invention throughout the world for the benefit of the assignee, and to execute all instruments proper to carry out the intent of this instrument.

The undersigned warrants that the rights and property herein conveyed are free and clear of any encumbrance.

EXECUTED under seal on this 28th day of October, 2011

at Tokyo, Japan.

(Place)

Witness:

\_\_\_\_\_

Norikazu Mizuno (L.S.)  
Norikazu Mizuno

\_\_\_\_\_

Tomohide Kato (L.S.)  
Tomohide Kato

\_\_\_\_\_

Takaaki Noda (L.S.)  
Takaaki Noda

(Although not mandatory, if possible,  
please subscribe appropriate notarization and obtain APOSTILLE)